



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q79466

Takashi TONEGAWA

Appln. No.: 10/761,256

Group Art Unit: 2813

Confirmation No.: 2575

Examiner: Thanh T. NGUYEN

Filed: January 22, 2004

For: SEMICONDUCTOR DEVICE HAVING A Cu INTERCONNECTION AND METHOD  
FOR MANUFACTURING THE SAME

**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated July 15, 2005, please amend the above-identified application as follows on the accompanying pages.

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